



Part Number : [760685001](#)

Product Description : Small Form-factor Pluggable Plus (SFP+) Stacked 2-by-6 Multi-Port Press Fit Connector without Lightpipe Ports, EMI Metal Gasket, 240 Circuits, Tin (Sn) Tails

Series Number : 76068

Status : Active

Product Category : High-Speed I/O Connectors



Documents & Resources

Drawings

[760685001_sd.pdf](#)

3D Models and Design Files

[STEP AP242](#)

[SOLIDWORKS](#)

[Creo](#)

[EE-76090-001-001.pdf](#)

[SP-76090-001-001.zip](#)

Specifications

[AS-75310-001-001.pdf](#)

[AS-76090-001-001.pdf](#)

[PK-75451-001-001.pdf](#)

[PS-75310-001-001.pdf](#)

Product Environment Compliance

Compliance

GADSL/IMDS	Not Relevant
China RoHS	 per SJ/T 11365-2006
EU ELV	Not Relevant
Low-Halogen Status	Low-Halogen per IEC 61249-2-21
REACH SVHC	Not Contained per per D(2022)4187-DC (10 June 2022)

EU RoHS	Compliant per EU 2015/863
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Compliance Statements

- EU RoHS
- REACH SVHC
- Low-Halogen

Industry Documents

- IPC 1752A Class C
- IPC 1752A Class D
- Molex Product Compliance Declaration
- IEC-62474
- chemSHERPA (xml)

Substances of Interest

- PFAS

EU RoHS Certificate of Compliance

Additional Product Compliance Information

Part Details

General

Status	Active
Category	High-Speed I/O Connectors
Series	76068
Description	Small Form-factor Pluggable Plus (SFP+) Stacked 2-by-6 Multi-Port Press Fit Connector without Lightpipe Ports, EMI Metal Gasket, 240 Circuits, Tin (Sn) Tails
Application	Module-to-Board
Component Type	Receptacle
Product Name	SFP Plus,SFP+
Type	Pluggable
UPC	800756907505

Agency

CSA	LR19980
UL	E29179

Electrical

Current - Maximum per Contact	0.5A
Data Rate	10.0 Gbps, 28.0 Gbps
Grounding to Panel	None
Shielded	Yes
Shield Type	EMI Gasket
Voltage - Maximum	120V AC (RMS)/DC

Physical

Boot Color	N/A
Circuits Detail	240
Circuits (Loaded)	240
Circuits (maximum)	240
Color - Resin	Black
Durability (mating cycles max)	100
Flammability	94V-0
Gender	Female
Keying to Mating Part	None
Lock to Mating Part	Yes
Material - Metal	High Performance Alloy (HPA)
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	114.014/g
Number of Rows	2
Orientation	Right Angle
Packaging Type	Tray
Panel Mount	No
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness - Recommended	1.57mm
PC Tail Length	2.07mm
Pitch - Mating Interface	0.80mm
Pitch - Termination Interface	0.80mm
Plating min - Mating	0.762µm
Plating min - Termination	0.762µm

Polarized to Mating Part	Yes
Polarized to PCB	Yes
Ports	12
Temperature Range - Operating	-40° to +85°C
Termination Interface Style	Through Hole - Compliant Pin
Waterproof / Dustproof	No

Solder Process Data

Lead-Free Process Capability	N/A
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Application Tooling